

Docket No.: 3008-0028
File No. 521.41457X00
Client No.: PHCF-01094



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Seigi AOYAMA et al.

Application S/N 09/892,630

Filed: June 28, 2001

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: Art Unit: 2827
:
: Examiner: T. Dinh
:
:

For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL COMPONENT
USING SAID LEAD-FREE SOLDER

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REQUEST FOR APPROVAL OF DRAWING AMENDMENT

Assistant Commissioner of Patents
Washington, D.C. 20231

Sir:

Approval of the changes to Figure(s) 6, 7A and 7B as shown on the attached photocopies, is courteously solicited. A copy of these Figure(s) with the changes marked in red is also attached.

Respectfully submitted,

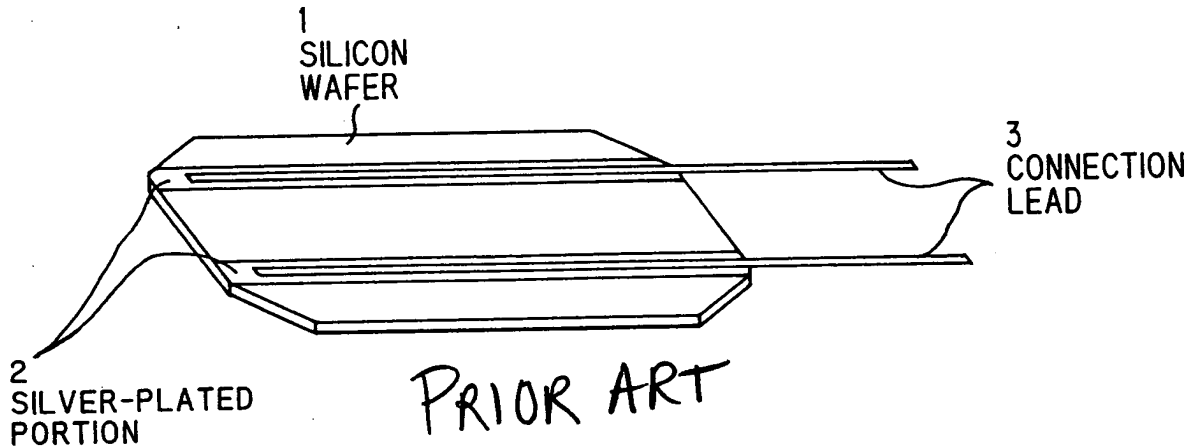
ANTONELLI, TERRY, STOUT AND KRAUS

Alfred A. Stadnicki
Registration No. 30,226

1300 North Seventeenth Street
Suite 1800
Arlington, Virginia 22209
Telephone: (703) 312-6600
Facsimile: (703) 312-6666
Date: September 9, 2002



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FIG. 6



OK
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FIG. 7A

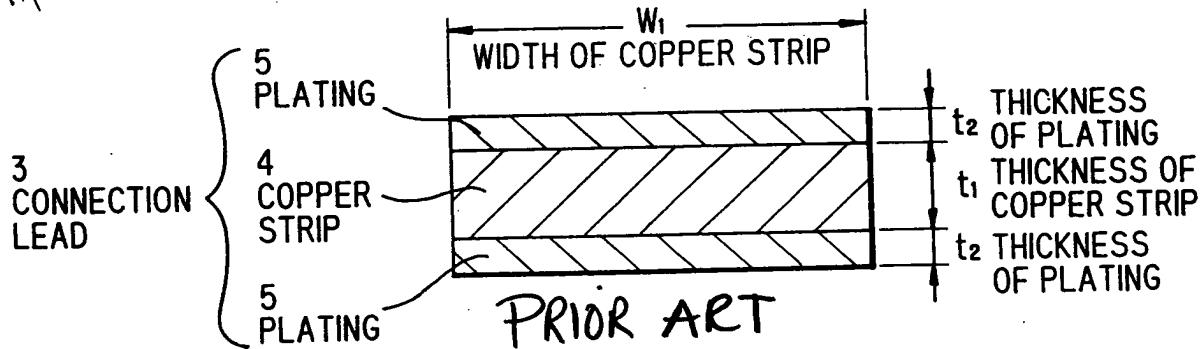
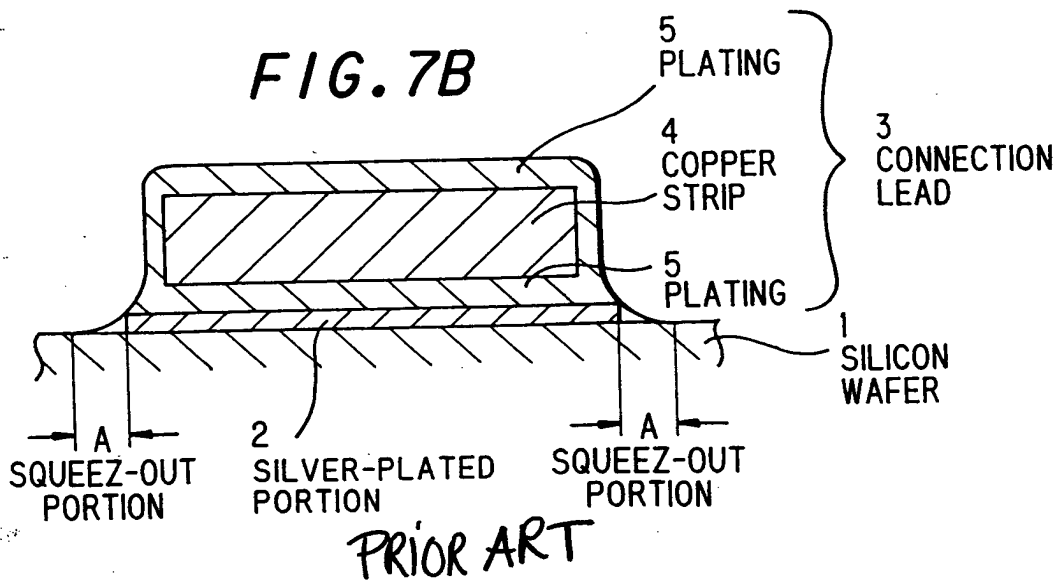


FIG. 7B





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FIG. 6

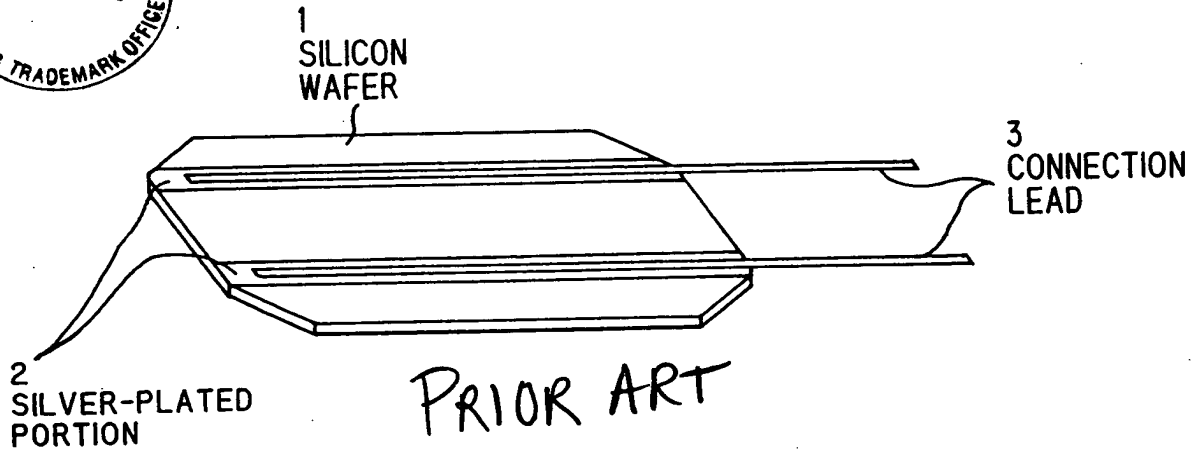


FIG. 7A

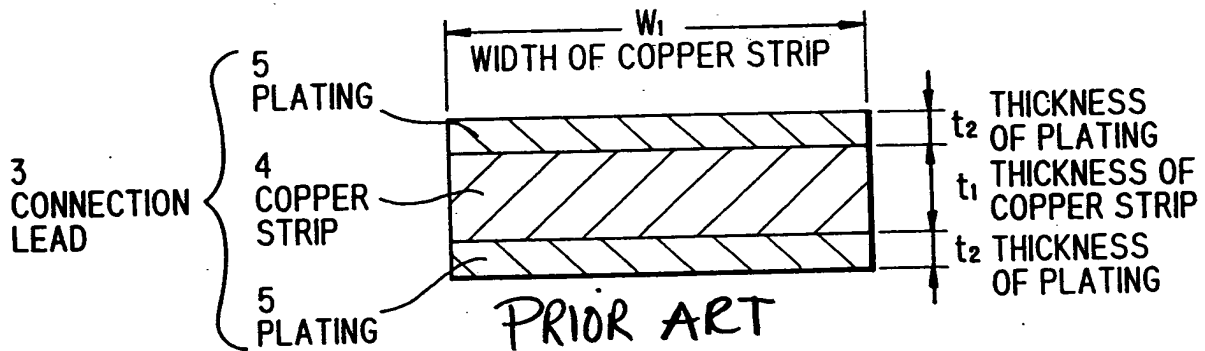


FIG. 7B

